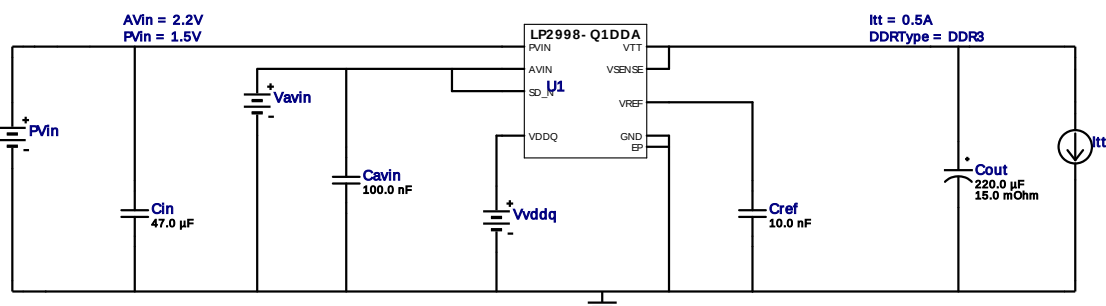


WEBENCH[®] Design Report

Design : 4807501/3 LP2998QMRE/NOPB
Design 3 - LP2998QMRE/NOPB

DDRTYPE = DDR3
PVIN = 1.5V
AVIN = 2.2V
I_{tt} = 0.5A
T_a = 25.0degC
VDDQ = 1.5V
VTT = 0.75V

Device = LP2998QMRE/NOPB
Topology = DDRLDO
Created = 9/29/16 7:01:28 PM
BOM Cost = \$1.47
BOM Count = 5
Total Pd = 0.38W



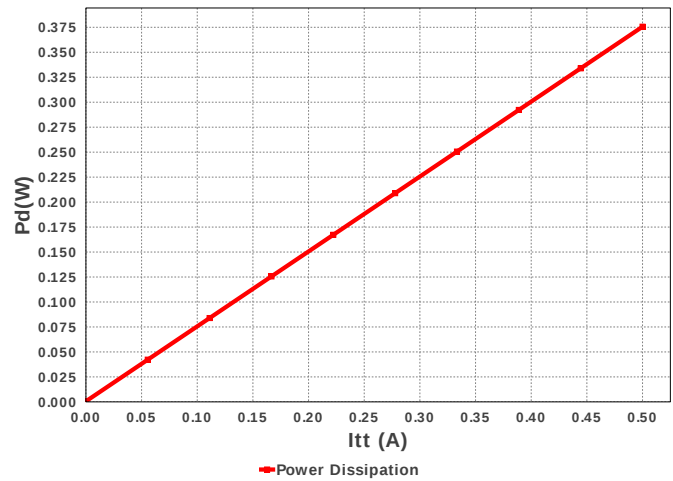
Electrical BOM

#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
1.	Cavin	MuRata	GRM155R60J104KA01D Series= X5R	Cap= 100.0 nF VDC= 6.3 V IRMS= 0.0 A	1	\$0.01	 0402 3 mm ²
2.	Cin	Taiyo Yuden	JMK212BJ476MG-T Series= X5R	Cap= 47.0 uF VDC= 6.3 V IRMS= 0.0 A	1	\$0.14	 0805 7 mm ²
3.	Cout	Panasonic	2R5TPE220MAFB Series= ?	Cap= 220.0 uF ESR= 15.0 mOhm VDC= 2.5 V IRMS= 2.0 A	1	\$0.50	 CAPSMT_6_B2S 17 mm ²
4.	Cref	MuRata	GRM155R60J103KA01D Series= X5R	Cap= 10.0 nF VDC= 6.3 V IRMS= 0.0 A	1	\$0.01	 0402 3 mm ²
5.	U1	Texas Instruments	LP2998QMRE/NOPB	Switcher	1	\$0.81	 DDA0008A 57 mm ²

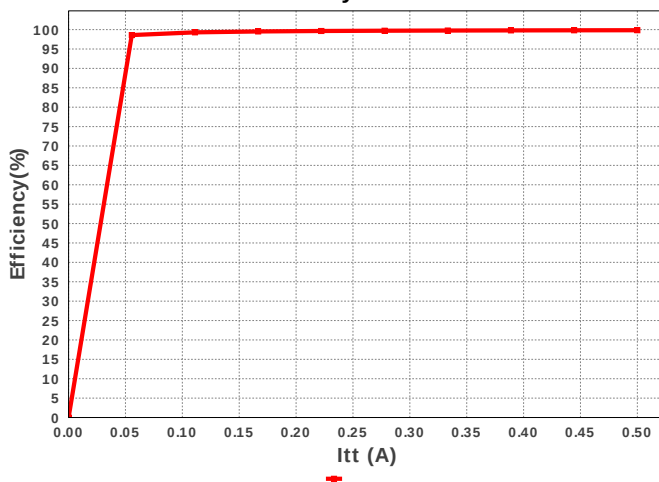
Quiescent Current Iq Vs. AVin



Power Dissipation Vs. Itt



Efficiency Vs. Itt



Operating Values

#	Name	Value	Category	Description
1.	DDR Type	DDR3	DDR Memory	DDR Memory Type
2.	BOM Count	5	General	Total Design BOM count
3.	FootPrint	87.0 mm ²	General	Total Foot Print Area of BOM components
4.	Total BOM	\$1.47	General	Total BOM Cost
5.	AVin_OP	2.2 V	Op_Point	Pvin operating point
6.	Itt_OP	500.0 mA	Op_Point	Itt Operating Point
7.	PVin_OP	1.5 V	Op_Point	Pvin operating point
8.	Ta_OP	25.0 degC	Op_Point	Operating Ambient Temperature
9.	Vddq_OP	1.5 V	Op_Point	Vddq operating point
10.	Vtt_OP	750.0 mV	Op_Point	Vtt operating point
11.	Efficiency	99.842 %	Op_point	Steady state efficiency
12.	IC Tj	41.151 degC	Op_point	IC junction temperature
13.	ICThetaJA	43.0 degC/W	Op_point	IC junction-to-ambient thermal resistance
14.	Total Pd	375.594 mW	Power	Total Power Dissipation

Design Inputs

#	Name	Value	Description
1.	AVin	2.2 A	AVin
2.	DDRTYPE	DDR3	DDRTYPE
3.	Itt	500.0 mA	Itt
4.	PVin	1.5 A	PVin
5.	application	DDRPower	application
6.	base_pn	LP2998-Q1	Base Product Number
7.	Ta	25.0 A	Ambient temperature

Design Assistance

1. **LP2998-Q1** Product Folder : <http://www.ti.com/product/lp2998> : contains the data sheet and other resources.

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